

HEADLINE NEWS

FOR IMMEDIATE RELEASE

Carsem

Press Contact: Rick Flowers

VP of World Wide Sales and Marketing

Telephone Number: +60 5 3123333

Fax Number: +60 5 3125333

Email Address: rflowers@m.carsems.com.my

Web site address: www.carsem.com

CARSEM REMAINS OPTIMISTIC ABOUT ITC PATENT LITIGATION

Ipoh, Malaysia -November 3, 2009-Carsem, a leading provider of turnkey packaging and test services to the semiconductor industry, announced today that an Administrative Law Judge (ALJ) has issued a supplemental Initial Determination (ID) in Carsem's on-going patent litigation with Amkor Technology in the U.S. International Trade Commission (ITC) in Washington, D.C.

The ALJ addresses issues related to the invalidity of Amkor's patents and supplements a prior ID issued in November 2005, in which he found all but four claims of one patent invalid, not infringed, and/or not enforceable at the ITC. Although Amkor requested an exclusion order against Carsem importing certain products, no exclusion order has been granted. Both of the ALJ's ID's will be reviewed by the full Commission, which is not expected to render a final decision until February 2010. After that, either party may seek further review in the Federal Appellate Court.

Peter Yates, Carsem's Group Managing Director, stated, "We look forward to the full Commission review of this matter, and are confident that when that review is completed, the ITC will find in Carsem's favor."

END

About Carsem

Carsem is a leading provider of turnkey packaging and test services to the semiconductor industry, and offers one of the widest ranges of package & test portfolios in the world. To meet the growing demands of the telecommunications and wireless markets for smaller, faster, thermally-efficient devices, Carsem's portfolio includes several advanced technologies, such as the Micro Leadframe Package (MLP), Small Scale Ball Grid Array (SSBGA), Flip Chip On Leadframe (FCOL), and a SiP (System-in-Package) capability. Carsem also offers a full range of turnkey test services for RF, mixed-signal, linear, digital and power devices. Our factories maintain world-class quality standards having achieved SAC Level 1, ISO-9001, ISO-14001, QS-9000, TS16949 certifications, and are supported with a global network of sales and engineering support offices. Carsem is a member of the Hong Leong Group with factories located in Ipoh, Malaysia, Suzhou, China and sales offices across the USA, the UK and Taiwan. Carsem, Inc. sales headquarters is located at 269 Mt. Hermon Road, Suite 104, Scotts Valley, CA 95066, phone (831) 438-6861, fax (831) 438-6863, web site: www.carsem.com.